

## Glued SAM data sheet SAM- $\lambda$ -A- $\tau$ -4.0-25.4g-c or 4.0-25.4g-e

GaAs chip area standard: 4.0 mm x 4.0 mm

optional: other dimensions on request

Chip thickness standard: 450 µm

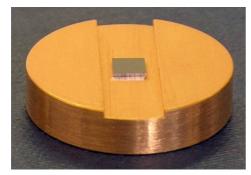
Front side protection the SAM is protected with a dielectric front layer.

The SAM chip is glued on a gold plated Cu-cylinder with 25.4 mm Ø using a thermal conducting glue.

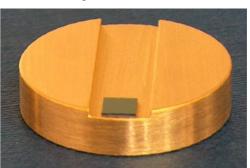
- The **standard** position of the SAM is at the center of the mount  $\rightarrow$  x = 4.0-25.4g-c.
- Optional the SAM can be mounted at the edge of the mount without extra charges.

 $\rightarrow$  x = 4.0-25.4g-e.

Center mounted SAM



Edge mounted SAM



## Mount

Cu-cylinder,  $\emptyset$  = 25.4 mm I = 6.0 mm

